

U.S. PAT. APP. ENTITLED: "FLIP-CHIP PACKAGE WITH UNDERFILL DAM THAT CONTROLS STRESS AT CHIP EDGES"; INVENTORS: HILTON ET AL.; ATTY. DKT. NO.: MTB001US

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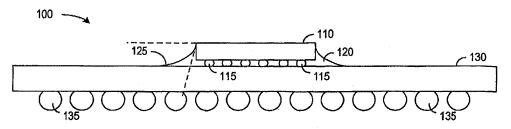
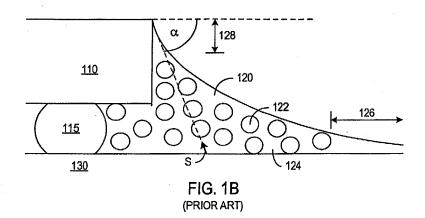


FIG. 1A (PRIOR ART)



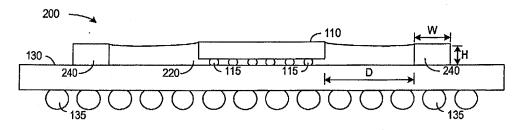
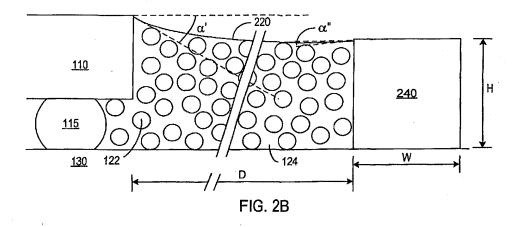


FIG. 2A

U.S. PAT. APP. ENTITLED: "FLIP-CHIP PACKAGE WITH UNDERFILL DAM THAT CONTROLS STRESS AT CHIP EDGES"; INVENTORS: HILTON ET AL.; ATTY. DKT. NO.: MTB001US

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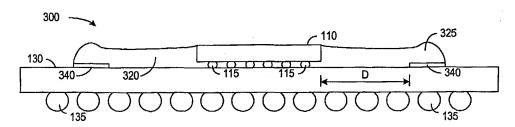


FIG. 3

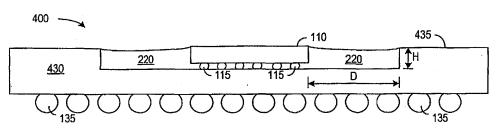


FIG. 4